

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	17	JENSEN-D JENSEN-DAVID-G JENSEN-DAVID-GLENN	US-PGPUB; USPAT	OR	OFF	2004/11/12 08:21
L2	30	JENSEN-D JENSEN-DAVID-G JENSEN-DAVID-GLENN	EPO; JPO; DERWENT	OR	OFF	2004/11/12 08:25
L3	330	(solder with (reflow apparatus system)) same test\$4 same (packag\$4 with (semiconductor ic integrated component microelectronic die dice chip))	US-PGPUB; USPAT	OR	ON	2004/11/12 11:48
L4	161	(solder near2 (reflow apparatus system)) same test\$4 same (packag\$4 with (semiconductor ic integrated component microelectronic die dice chip))	US-PGPUB; USPAT	OR	ON	2004/11/12 08:32
L5	27	(solder with reflow\$6) and test\$4 and (packag\$4 with (semiconductor ic integrated component microelectronic))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 09:27
L6	8	(solder with reflow) and ((cur\$5 resin encapsula\$6) with (temperature degree ?c)) and test\$4	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 10:16
L7	56	((solder with reflow) and ((cura\$4 curi\$4 cure\$4 resin encapsula\$6) with (temperature degree ?c))) and (packag\$4 with (semiconductor ic integrated component microelectronic))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 10:20
L8	91	((solder with reflow) same test\$4) and ((packag\$4 with (semiconductor ic integrated component microelectronic)) same ((cur\$5 resin encapsula\$6) with (temperature degree ?c)))	US-PGPUB; USPAT	OR	ON	2004/11/12 10:32
L9	164	((solder with reflow) and test\$4 and (packag\$4 with (semiconductor ic integrated component microelectronic)) and ((cur\$5 resin encapsula\$6) with (temperature degree ?c))) and (438/15.ccls. 438/106.ccls. 438/127.ccls. 438/612.ccls.)	US-PGPUB; USPAT	OR	ON	2004/11/12 11:03
L10	1	((solder with reflow) and preheat\$5) and test\$4	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 11:08
L11	117	(solder with reflow) with preheat\$5	US-PGPUB; USPAT	OR	ON	2004/11/12 11:46

L12	5	((solder with reflow) and preheat\$5) and (packag\$4 with (semiconductor ic integrated component microelectronic))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 11:09
L16	1681	solder with (reflow\$6 plat\$6) with (apparatus system)	US-PGPUB; USPAT	OR	ON	2004/11/12 12:55
L17	135	16 same (packag\$4 with (semiconductor ic integrated component microelectronic die dice chip))	US-PGPUB; USPAT	OR	ON	2004/11/12 12:02
L18	1232	solder with (reflow\$6 plat\$6) with (apparatus system)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 11:52
L19	58	18 and (packag\$4 with (semiconductor ic integrated component microelectronic die dice chip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/12 12:51
L20	6329	29/25.01.ccls. 29/25.02.ccls. 29/25.03.ccls. 324/765.ccls. 228/42.ccls. 228/232.ccls. 438/15.ccls. 438/612.ccls.	US-PGPUB; USPAT	OR	ON	2004/11/12 12:53
L21	133	16 and 20	US-PGPUB; USPAT	OR	ON	2004/11/12 12:56
L22	1126	20 and (solder with (reflow\$6 plat\$6 apparatus system))	US-PGPUB; USPAT	OR	ON	2004/11/12 13:27